



Material Content Data Sheet



Sales Product Name	ESD3V3U1U-02LS E6327				Issued		30. January 2015	
MA#	MA000446580							
Package	PG-TSSLP-2-1				Weight*		0.15 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.23		2335	
	noble metal	gold	7440-57-5	0.001	0.90		9044	
	inorganic material	silicon	7440-21-3	0.010	6.70	7.83	67034	78413
leadframe	non noble metal	nickel	7440-02-0	0.036	24.33	24.33	243273	243273
wire	noble metal	gold	7440-57-5	0.003	1.93	1.93	19265	19265
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		288	
	organic material	carbon black	1333-86-4	0.001	0.58		5820	
	plastics	epoxy resin	-	0.012	7.85		78540	
	inorganic material	silicondioxide	60676-86-0	0.074	49.73	58.19	497139	581787
leadfinish	noble metal	gold	7440-57-5	0.004	2.75	2.75	27513	27513
plating	noble metal	silver	7440-22-4	0.007	4.97	4.97	49749	49749
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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